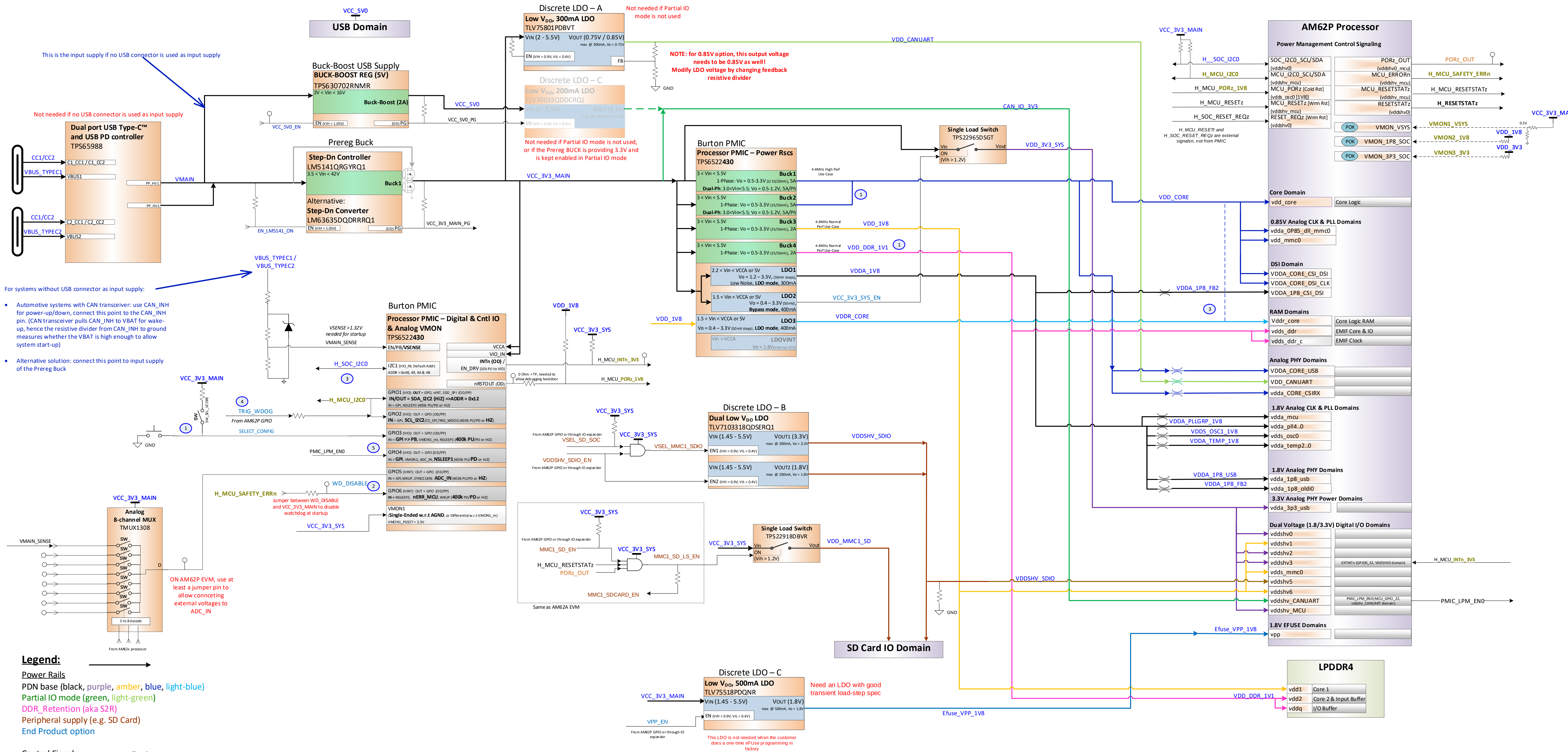


AM62P EVM with Burton PMIC



Notes:

- SELECT_CONFIG:** TPS65224 PMIC initially at start-up checks the level of GPIO3.
 - if SW_SEL_VCORE is open -> GPIO3 open-connect (default config for AM62P EVM):
 - normal core speed VDD_CORE=0.75V (BUCK1/2 VOUT=0.75V)
 - if SW_SEL_VCORE is closed -> GPIO3 is pulled-up with 10k to VCCA:
 - high core speed VDD_CORE = 0.85V (BUCK1/2 VOUT=0.85V)

=> any level change on GPIO3 after power-up (before start of power-up sequence) is ignored by the PMIC
=> after start-up, PMIC re-configures GPIO3 into PB with internal pull-up

Notes:

- DISABLE_WDOG:** TPS65224 PMIC reads the level at the GPIO6 pin during the power-up sequence.
 - If the level at the GPIO6 pin is high after start-up of VCC_3V3_MAIN (jumper between WD_DISABLE and VCC_3V3_MAIN closed), the PMIC sets the WD_PWRHOLD bit to disable the long-window time-out of the watchdog.
 - If the level at the GPIO6 pin is low after start-up of VCC_3V3_MAIN (jumper between WD_DISABLE and VCC_3V3_MAIN open, hence GPIO6 is low through internal PD), the PMIC does not set the WD_PWRHOLD bit and hence the long-window time-out of the watchdog is activated
- For single I2C usage: use I2C from MCU, or use both SoC&MCU I2C as multi-master**
- GPIO2 can be re-configured into TRIG_WDOG after startup. In order to use GPIO2 as TRIG_WDOG, configuration bits GPIO2_SEL need to be set to 0x3
- GPIO4 (NSLEEP): select LPDDR4/DDR4 use-case. (AM62P EVM only supports LPDDR4, so GPIO4 has no pull-down and is connected to PMIC_LPM_ENO signal from AM62P if RETENTION mode is used)
 - no pull-down: LPDDR4 use-case
 - 10k pull-down: DDR4 use-case (not supported on AM62P EVM)

=> for case a): after start-up, PMIC PFSM re-configures GPIO4 into NSLEEP1 with internal pull-up. AM62P EVM use-case with LPDDR4: signal PMIC_LPM_ENO from AM62P is used at PMIC GPIO4 to:

 - put PMIC into RETENTION if PMIC_LPM_ENO=0
 - wake-up from RETENTION if PMIC_LPM_ENO=1

=> in case of 10k pull-down at GPIO4 (DDR4 use-case), either use GPIO3 as PB for wake-up&power-down, or, if GPIO3 has no ext pull-up, use GPIO3 as NSLEEP1 (SW reconfigures GPIO3 into NSLEEP1)
=> in case of 10k pull-down at GPIO4 (DDR4 use-case) and 10k pull-up at GPIO3, customer can, if I2C2 is not used, re-configure GPIO1 into NSLEEP2 to put PMIC into RETENTION with PMIC_LPM_ENO signal

7.9.2.2.1 Power-Up Sequencing

Figure 7-5 describes the device power-up sequencing.

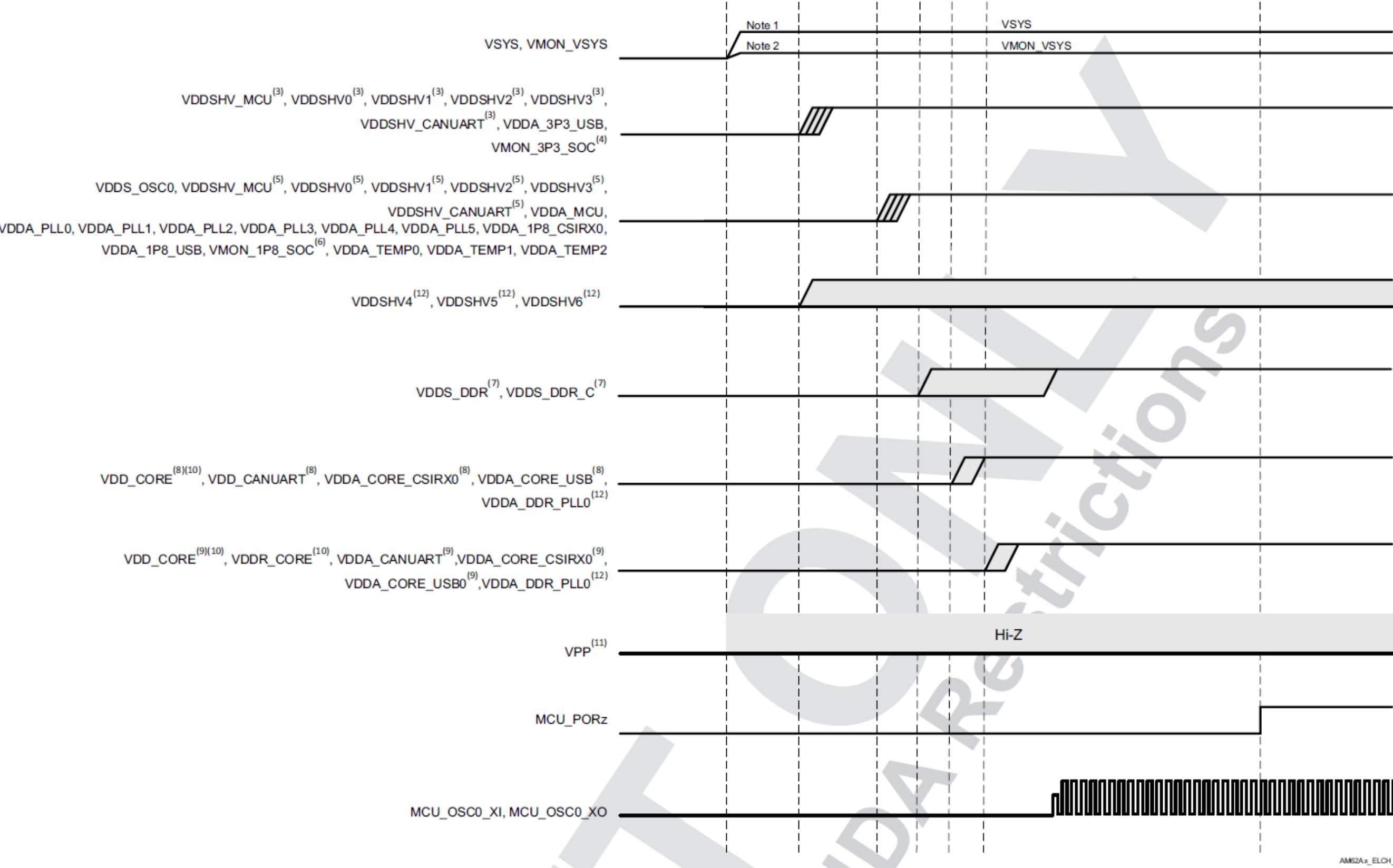


Figure 7-5. Power-Up Sequencing

- VSYS represents the name of a supply which sources power to the entire system. This supply is expected to be a pre-regulated supply that sources power management devices which source all other supplies.
- VMON_VSYS input is used to monitor VSYS via an external resistor divider circuit. For more information, see the *System Power Supply Monitor Design Guidelines*.
- VDDSHV_CANUART, VDDSHV_MCU, and VDDSHVx [x=0-6] are dual voltage IO supplies which can be operated at 1.8V or 3.3V depending on the application requirements. VDDSHV_CANUART shall be connected to an always-on power source when using Partial IO low power mode, or conencted to any valid IO power source when not using Partial IO low power mode. When VDDSHV_CANUART is not connected to an always-on power source and is operating at 3.3V, it shall be ramped up with other 3.3V supplies during the 3.3V ramp period defined by this waveform. When any of the VDDSHV_MCU and VDDSHVx [x=0-6] IO supplies are operating at 3.3V, they shall be ramped up with other 3.3V supplies during the 3.3V ramp period defined by this waveform.
- The VMON_3P3_SOC input is used to monitor supply voltage and shall be connected to the respective 3.3V supply source.
- VDDSHV_CANUART, VDDSHV_MCU, and VDDSHVx [x=0-6] are dual voltage IO supplies which can be operated at 1.8V or 3.3V depending on the application requirements. VDDSHV_CANUART shall be connected to an always-on power source when using Partial IO low power mode, or conencted to any valid IO power source when not using Partial IO low power mode. When VDDSHV_CANUART is not connected to an always-on power source and is operating at 1.8V, it shall be ramped up with other 1.8V supplies during the 1.8V ramp period defined by this waveform. When any of the VDDSHV_MCU and VDDSHVx [x=0-6] IO supplies are operating at 1.8V, they shall be ramped up with other 1.8V supplies during the 1.8V ramp period defined by this waveform.
- The VMON_1P8_SOC input is used to monitor supply voltage and shall be connected to the respective 1.8V supply source.
- VDDSD_DDR and VDDSD_DDR_C are expected to be powered by the same source such that they ramp together.
- VDD_CANUART shall be connected to an always-on power source when using Partial IO low power mode, or connected to the same power source as VDD_CORE when not using Partial IO low power mode. VDD_CORE, VDDA_CORE_CSIRX0, VDDA_CORE_USB, and VDDA_DDR_PLL0 shall always be sourced from the same power source and can be operated at 0.75V or 0.85V. When these supplies are operating at 0.75V, they shall be ramped up prior to all 0.85V supplies as shown in this waveform.
- VDD_CANUART shall be connected to an always-on power source when using Partial IO low power mode, or connected to the same power source as VDD_CORE when not using Partial IO low power mode. VDD_CORE, VDDA_CORE_CSIRX0, VDDA_CORE_USB, and VDDA_DDR_PLL0 shall be sourced from the same power source and can be operated at 0.75V or 0.85V. When these supplies are operating at 0.85V, they shall be ramped up with other 0.85V supplies during the 0.85V ramp period defined by this waveform.
- The potential applied to VDDR_CORE must never be greater than the potential applied to VDD_CORE + 0.18V during power-up or power-down. This requires VDD_CORE to ramp up before and ramp down after VDDR_CORE when VDD_CORE is operating at 0.75V. VDD_CORE does not have any ramp requirements beyond the one defined for VDDR_CORE. VDD_CORE and VDDR_CORE are expected to be powered by the same source so they ramp together when VDD_CORE is operating at 0.85V.
- VPP is the 1.8V eFuse programming supply, which shall be left floating (HiZ) or grounded during power-up/down sequences and during normal device operation. This supply shall only be sourced while programming eFuse.
- VDDSHV4, VDDSHV5, and VDDSHV6 were designed to support power-up, power-down, or dynamic voltage change without any dependency on other power rails. This capability is required to support UHS-I SD Cards.

7.9.2.2.2 Power-Down Sequencing

Figure 7-6 describes the device power-down sequencing.

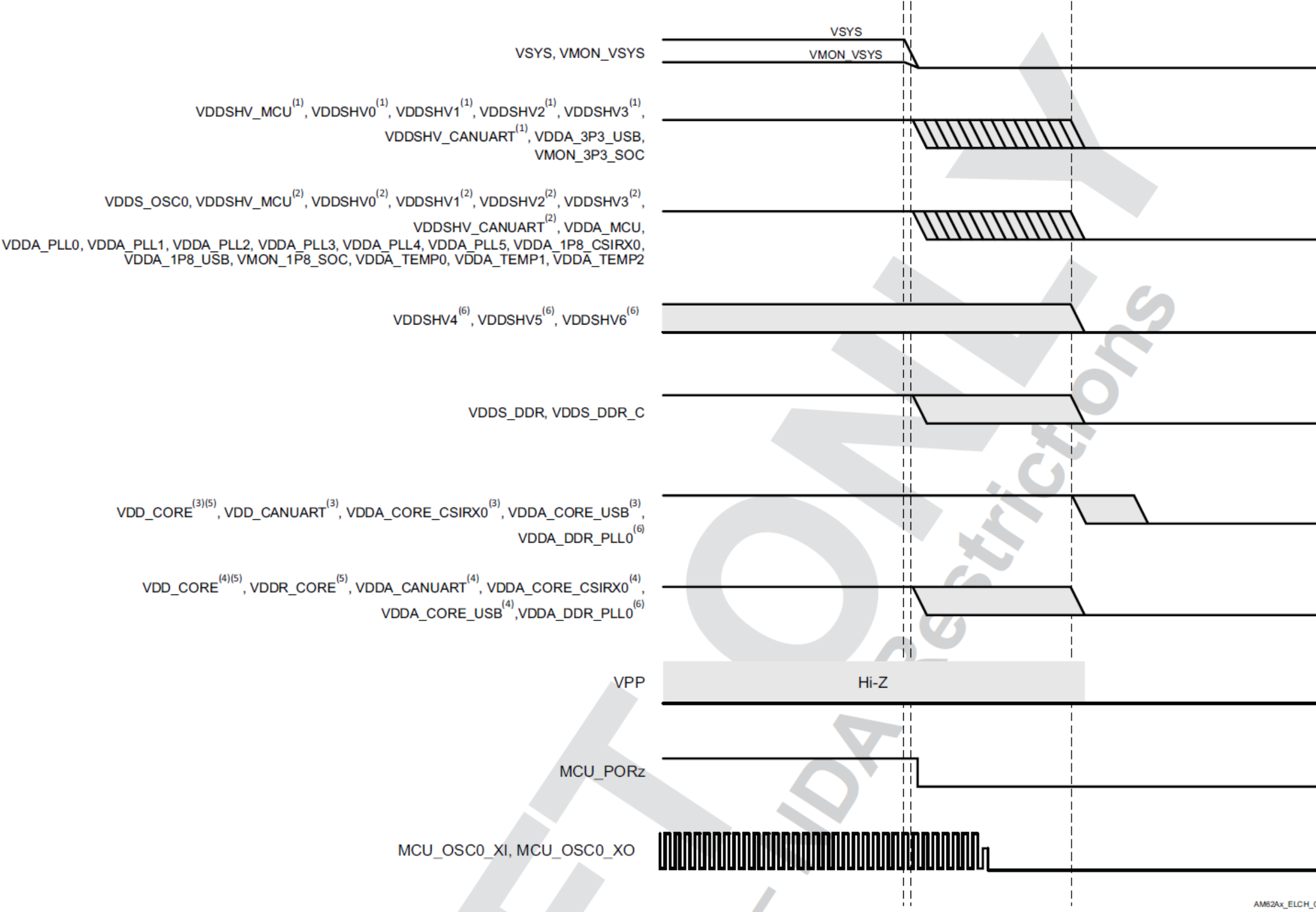


Figure 7-6. Power-Down Sequencing

- VDDSHV_CANUART, VDDSHV_MCU, and VDDSHVx [x=0-6] when operating at 3.3V.
- VDDSHV_CANUART, VDDSHV_MCU, and VDDSHVx [x=0-6] when operating at 1.8V.
- VDD_CORE, VDD_CANUART, VDDA_CORE_CSIRX0, VDDA_CORE_USB, and VDDA_DDR_PLL0 when operating at 0.75V.
- VDD_CORE, VDD_CANUART, VDDA_CORE_CSIRX0, VDDA_CORE_USB, and VDDA_DDR_PLL0 when operating at 0.85V.
- The potential applied to VDDR_CORE must never be greater than the potential applied to VDD_CORE + 0.18V during power-up or power-down. This requires VDD_CORE to ramp up before and ramp down after VDDR_CORE when VDD_CORE is operating at 0.75V. VDD_CORE does not have any ramp requirements beyond the one defined for VDDR_CORE. VDD_CORE and VDDR_CORE are expected to be powered by the same source so they ramp together when VDD_CORE is operating at 0.85V.
- VDDSHV4, VDDSHV5, and VDDSHV6 were designed to support power-up, power-down, or dynamic voltage change without any dependency on other power rails. This capability is required to support UHS-I SD Cards.

7.9.2.1 Power Supply Slew Rate Requirement

To maintain the safe operating range of the internal ESD protection devices, TI recommends limiting the maximum slew rate of supplies to be less than 18 mV/μs. For instance, as shown in Figure 7-2, TI recommends having the supply ramp slew for a 1.8-V supply of more than 100 μs.

Figure 7-2 describes the Power Supply Slew Rate Requirement in the device.

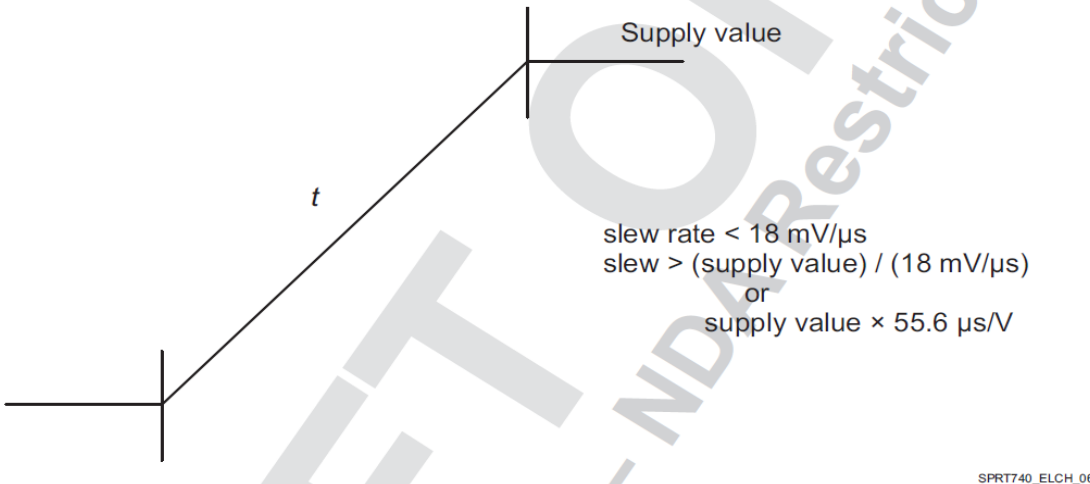
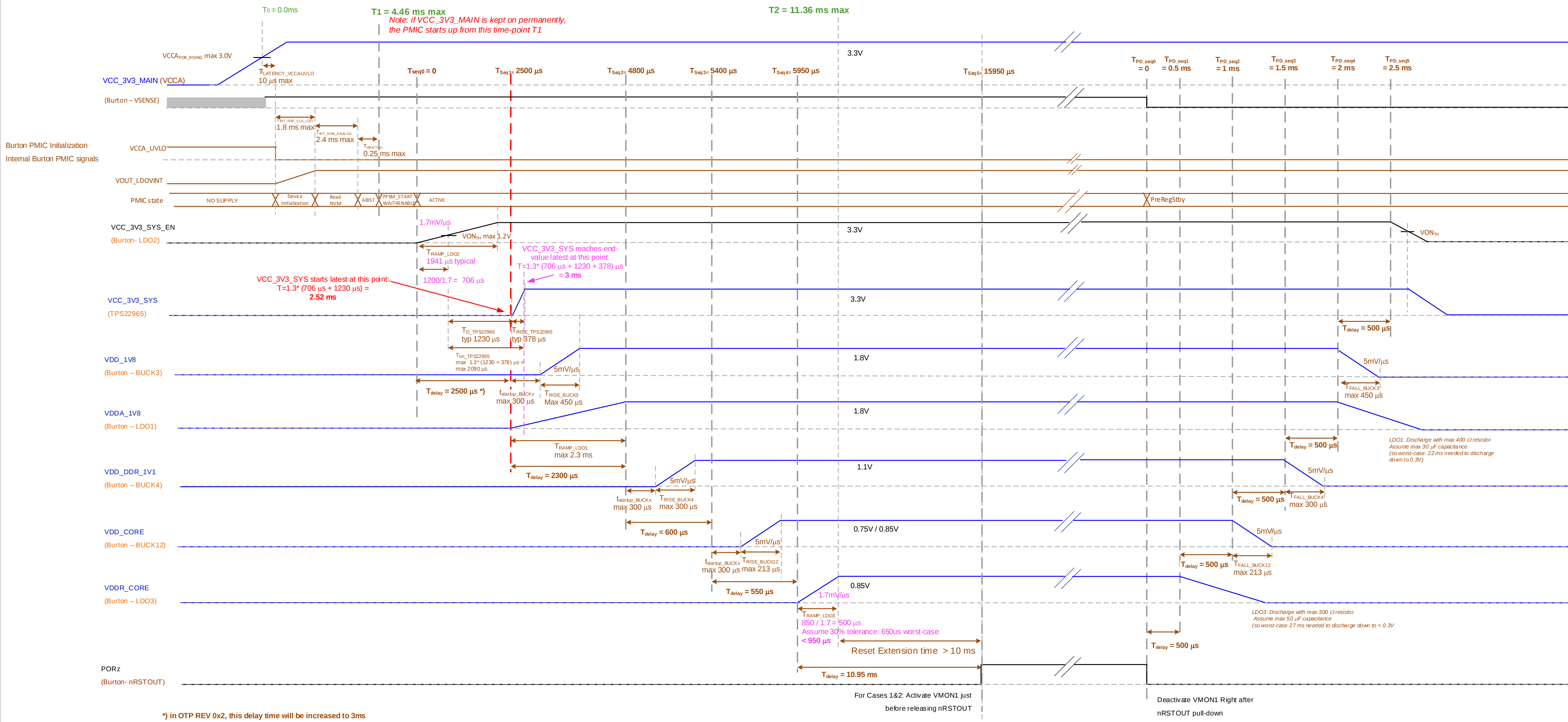


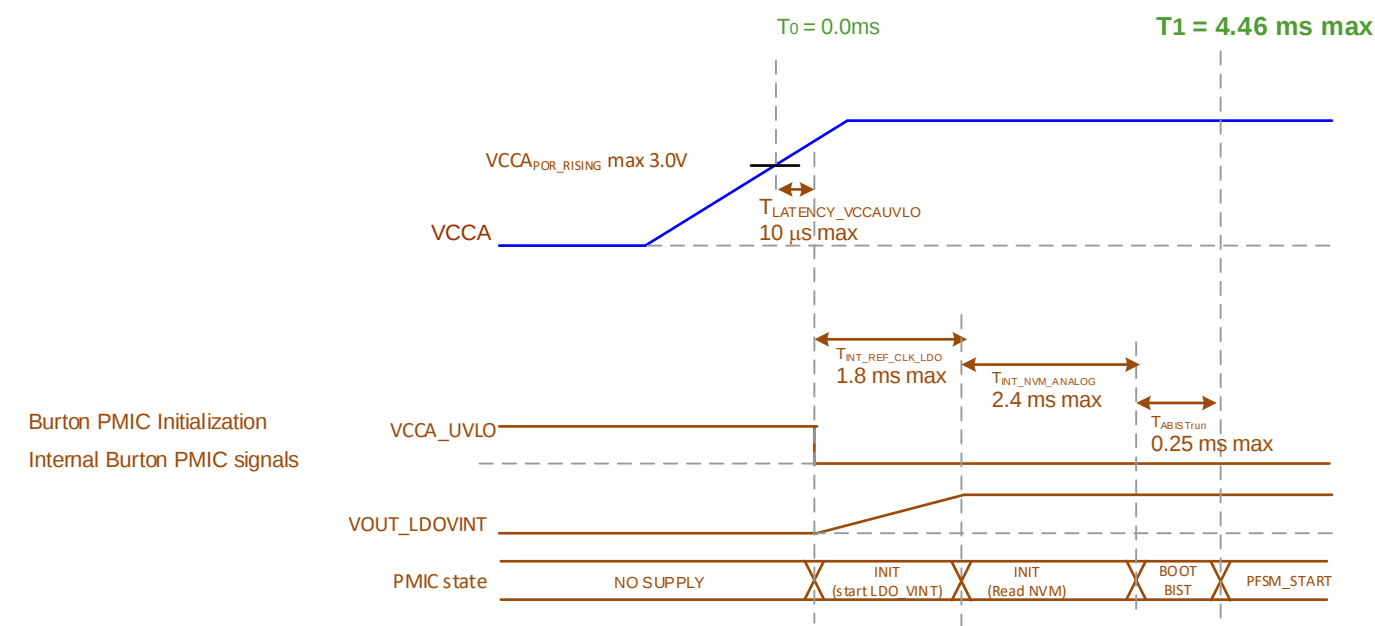
Figure 7-2. Power Supply Slew and Slew Rate

Power Up Sequence Burton PMIC

Legend:
 System Time
 Device Time
 Board Nets Board Control Signals
 Power Resource
OTP Set Values: (Resource, Current Capacity, Boot Voltage, Delay After Enable [us], Slew Rate [mV/us])



Legend:
System Time
Device Time
Board Nets
Board Control Signals
Power Resource
OTP Set Values: (Resource, Current Capacity, Boot Voltage, Delay After Enable [us], Slew Rate [mV/us])



Change Log

V1.0	11/30/2022	1. Initial Creation and Mapping
V1.1	01/24/2023	Updated PDN diagram (GPIO mapping), GPIO select pin
V1.2	02/01/2023	Corrected LDO2 and LDO3 minimum input voltage, added recommended component number for the NMOS at the VMAIN_SENSE resistive divider
V1.3	02/09/23	Review with Sirara apps team. - Put additional notes in red (high-current LDO for VPP, VDD_CANUART voltage from LDO needs to be the same as VDD_CORE, even of 0.85V option) - Added 3-input AND gate for enabling the SD_CARD (processor power-on reset connected to the first input, the processor warm reset connected to the second input, and a GPIO connected to the third input) - Modified Note 6 : SD-CARD voltage from LDO2 can only be changed from 3.3V to 1.8V by setting the TRIGGER_I2C_5 bit through I2C. Clearing bit TRIGGER_I2C_5 bit through I2C5 does not set the LDO2 voltage back to 3.3V. => Only after a re-enable of the SD_CARD, so when the signal at PMIC GPIO2 (MMC_SDCARD_EN signal) has a new rising edge, the LDO2 is re-enabled with 3.3V. - Modified Note 3 : level of WD_DISABLE at GPIO6 is read after VCC_3V3_SYS comes up (not right at startup before the processor supply is enabled).
V1.4	03/13/23	Changed GPIO4 into VSEL_SD_SOC, and added footnote 7)
V1.5	03/16/23	Removed SD-Card support from Burton PMIC – SD_IO voltage created with external dual-output LDO. Burton LDO2 used for VSYS_3V3 – removed external Load-Switch Updated GPIO assignment of Burton PMIC Removed mux for PMIC_LPM_EN signal Removed power-fet from VMAIN resistive divider
V1.6	03/23/2023	Connected VIO and nINT pull-up resistor to VCC_3V3_SYS
V1.7	03/27/2023	Corrected schematic note 1), added schematic note 5)
V1.8	04/27/2023	Updated schematic note 1) by mentioning the internal pull-up at GPIO3 when configured as Push-Button, and updated proposed circuit at GPIO3. Connected VIO_IN to VCCA
V1.9	05/08/2023	Added control logic for the VDD_SDIO discrete dual-output LDO Added 6A load-switch for VSYS_3V3 (controlled with LDO2 from PMIC) Updated pin/domain names in AM62P symbol, and added the DSI domain
V2.0	05/09/2023	Changed part number for VDD_CANUART LDO into TLV75801PDBVT
V2.1	05/15/2023	Added resistive divider connection from VCC_SYS_3V3 to PMIC VMON1 Added PowerUpSequence_Burton waveforms
V2.2	05/23/2023	Removed resistive divider connection from VCC_SYS_3V3 to PMIC VMON1 (reduce quiescent current in DDR-retention) Updated note 5 for GPIO4 in schematics (Note 5 is not relevant for the AM62P EVM, but is relevant if customers want to use the AM62P with DDR4 instead of LPDDR4)
V2.3	07/26/2023	Updated timing diagram for Power-Up Sequence
V2.4	11/02/2023	Added USB-connectors to schematics, and corrected connection for the resistive divider connected to the VSENSE pin of the PMIC. Updated timing diagram for Power-Up Sequence